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ICS 31.180
CCS L30

SJ

# INDUSTRY STANDARD OF THE PEOPLE'S REPUBLIC OF CHINA

# SJ/T 11741-2019

## Test method for flex resistance of flexible printed circuit materials

挠性印制电路材料的耐挠曲性测试方法

**(English Translation)**

**Implemented on: April 1, 2020**

**Issued by: Ministry of Industry and Information Technology**

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## 1 Foreword

SJ/T 11741-2019 was issued by Ministry of Industry and Information Technology on 11 November 2019 and has been in force since 1 April 2020.

The SJ/T prefix marks a recommended standard. It is not law in itself: it becomes binding when a contract names it, when a regulation or a mandatory standard refers to it, or when a producer declares conformity with it.

The document runs to 8 pages in English translation.

## 2 Scope Preview

This standard specifies a test method for flex resistance of flexible printed circuit materials. This method is applicable to copper foil and flexible copper clad laminate for flexible copper clad laminate.



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SJ/T 11741-2019 falls under ICS 31.180, in the field of electronics.

This catalogue holds 221 other SJ/T standards in that field.

In this catalogue, SJ/T standards carry edition years from 1980 to 2026.

## 3 About this standard

Sector: Electronics Industry Standard (Recommended)

Issued by: Ministry of Industry and Information Technology

English translation: about 8 pages (approximate)

Chinese original: about 7,710 characters

## 4 Related standards

Standards on related subjects:

GB/T 12631-2017 - Test method for resistance of conductors of printed boards

SJ/T 11993-2025 - Testing method for the pad cratering of printed circuit board assembly

SJ/T 11742-2019 - Thermally conductive non-prepreg prepreg for printed circuit

## 5 Classification and status

International classification (ICS): 31.180

Chinese Standard Classification (CCS): L 30

Prefix SJ/T: recommended standard.



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